

Dual N-CHANNEL ENHANCEMENT MODE POWER MOSFET

MTDN4228Q8

Description

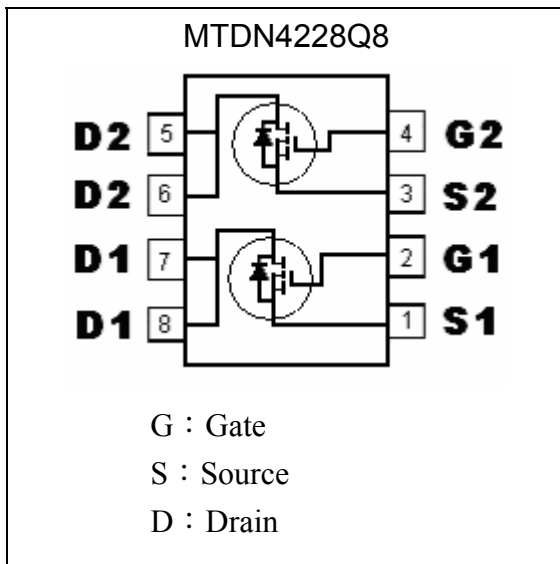
The MTDN4228Q8 provides the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness.

The SOP-8 package is universally preferred for all commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters.

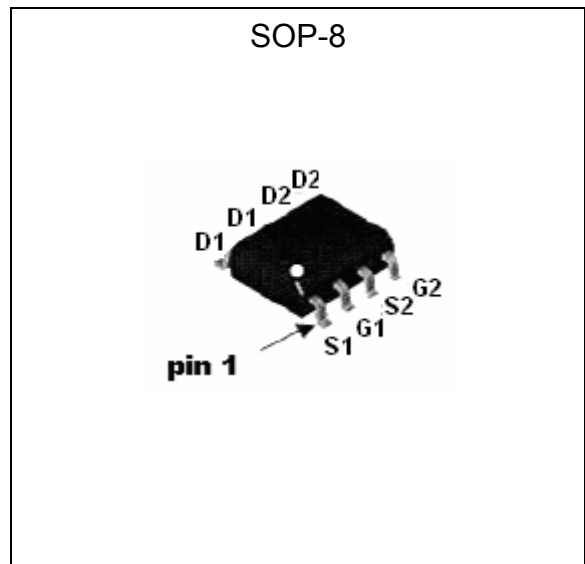
Features

- $R_{DS(ON)}=40m\Omega@V_{GS}=4.5V, I_D=4A$
- Simple drive requirement
- Low on-resistance
- Fast switching speed
- Dual N-ch MOSFET package
- Pb-free lead plating package

Equivalent Circuit



Outline



Ordering Information

Device	Package	Shipping	Marking
MTDN4228Q8	SOP-8 (Pb-free lead plating package)	3000 pcs / Tape & Reel	4228SS



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Drain-Source Breakdown Voltage	BVDSS	30	V
Gate-Source Voltage	VGS	±20	V
Continuous Drain Current @TA=25 °C (Note 1)	ID	6.8	A
Continuous Drain Current @TA=70 °C (Note 1)	ID	5.5	A
Pulsed Drain Current (Note 2)	IDM	40	A
Total Power Dissipation @ TA=25 °C	Pd	2	W
Linear Derating Factor		0.016	W / °C
Operating Junction Temperature	Tj	-55~+150	°C
Storage Temperature	Tstg	-55~+150	°C
Thermal Resistance, Junction-to-Ambient	Rth,ja	62.5	°C/W

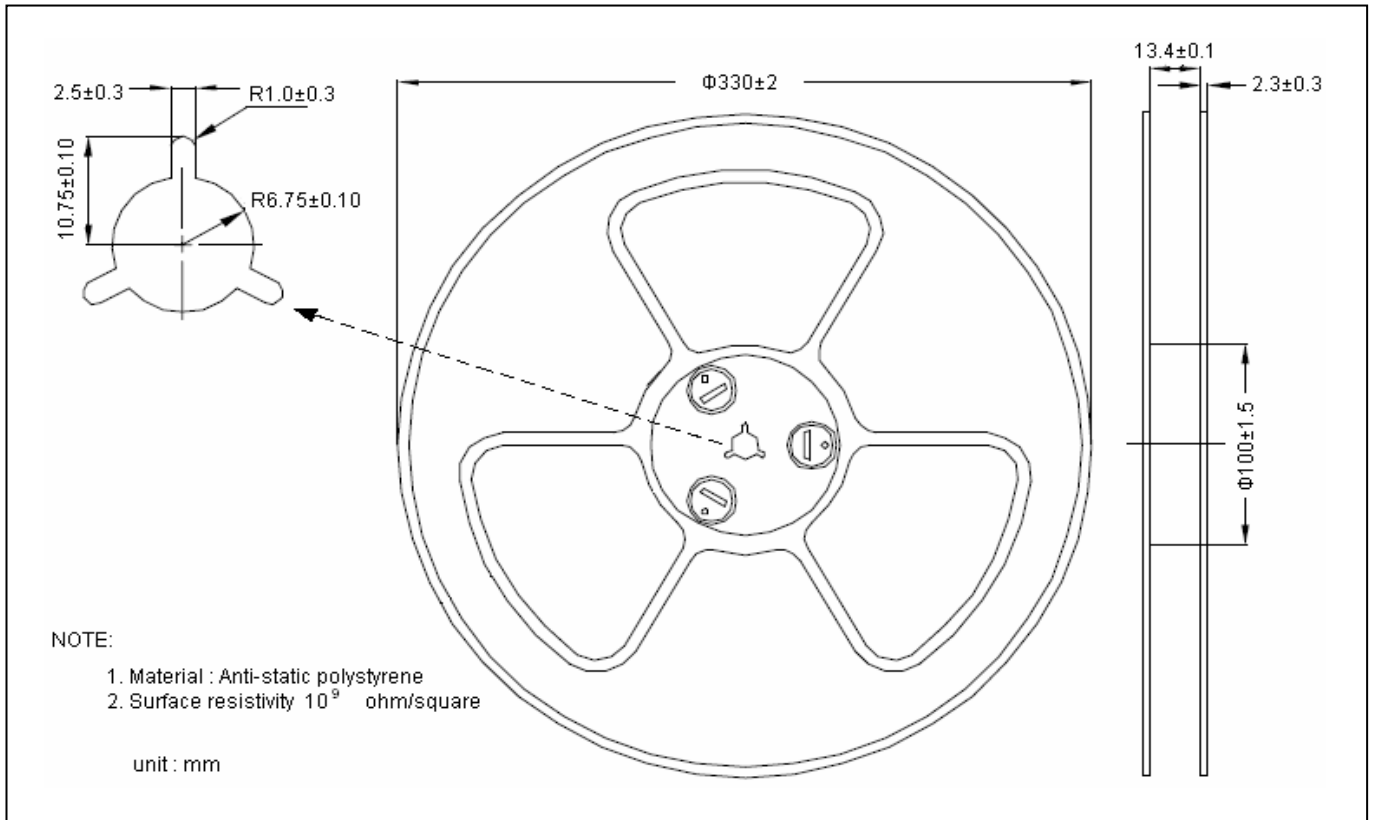
Note : 1.Surface mounted on 1 in² copper pad of FR-4 board, t≤10s.
 2.Pulse width limited by maximum junction temperature.

Electrical Characteristics (Ta=25°C)

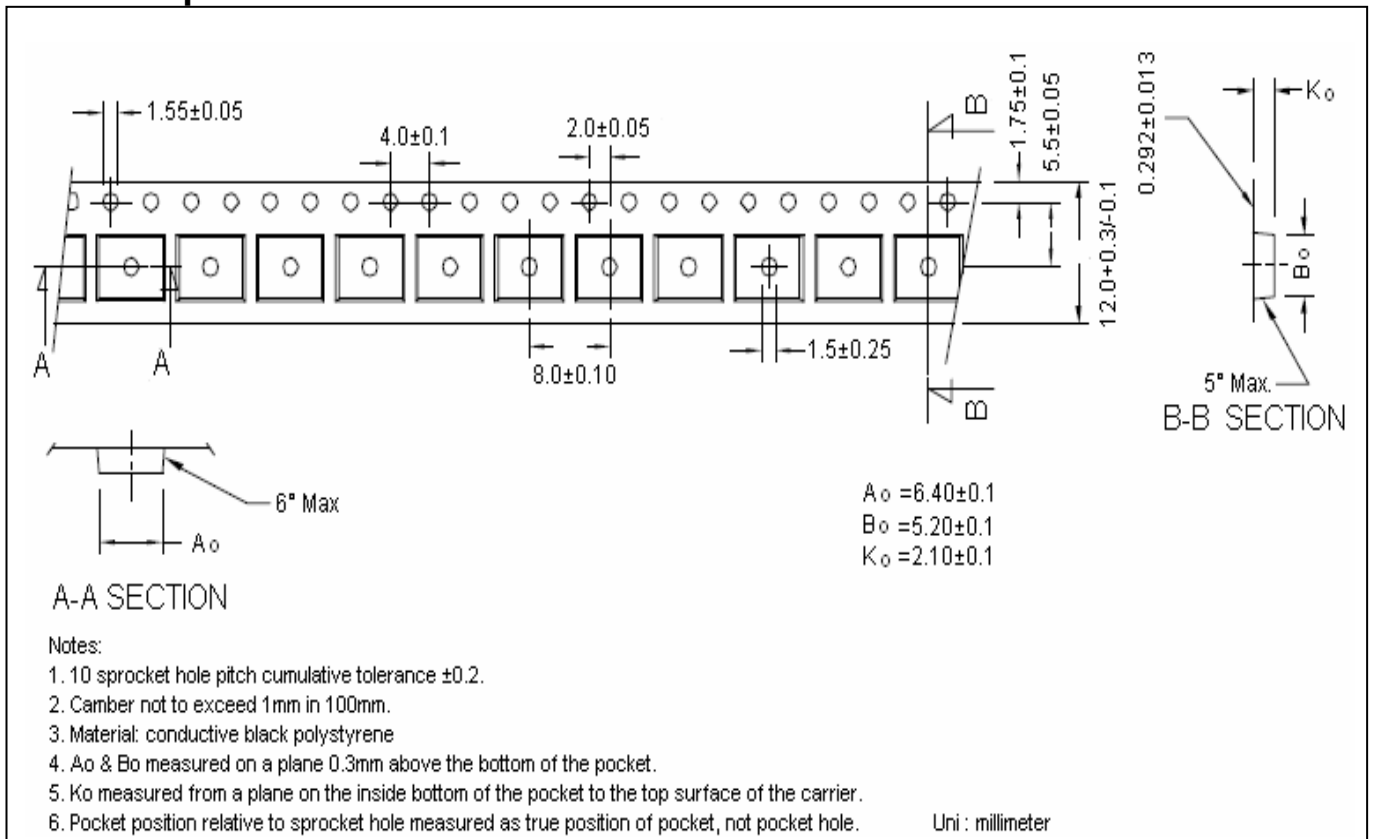
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVDSS	30	-	-	V	VGS=0, ID=250µA
VGS(th)	1	-	3	V	VDS=VGS, ID=-250µA
IGSS	-	-	±100	nA	VGS=±20V, VDS=0
IDSS	-	-	1	µA	VDS=30V, VGS=0
*RDS(ON)	-	-	26	mΩ	ID=6A, VGS=10V
	-	-	40		ID=4A, VGS=4.5V
*GFS	-	15	-	S	VDS=10V, ID=5A
Ciss	-	580	930	pF	VDS=25V, VGS=0, f=1MHz
Coss	-	150	-		
Crss	-	108	-		
td(ON)	-	10	-	ns	VDD=15V, ID=1A, VGS=10V, RGEN=3.3Ω, RD=15Ω
tr	-	9	-	ns	
td(OFF)	-	18	-	ns	
tr	-	6	-	ns	
Qg	-	9	15	nC	VDS=24V, ID=6.8A, VGS=4.5V,
Qgs	-	2	-	nC	
Qgd	-	6	-	nC	
*VSD	-	-	1.3	V	VGS=0V, ISD=1.7A

*Pulse Test : Pulse Width ≤380µs, Duty Cycle ≤2%

Reel Dimension



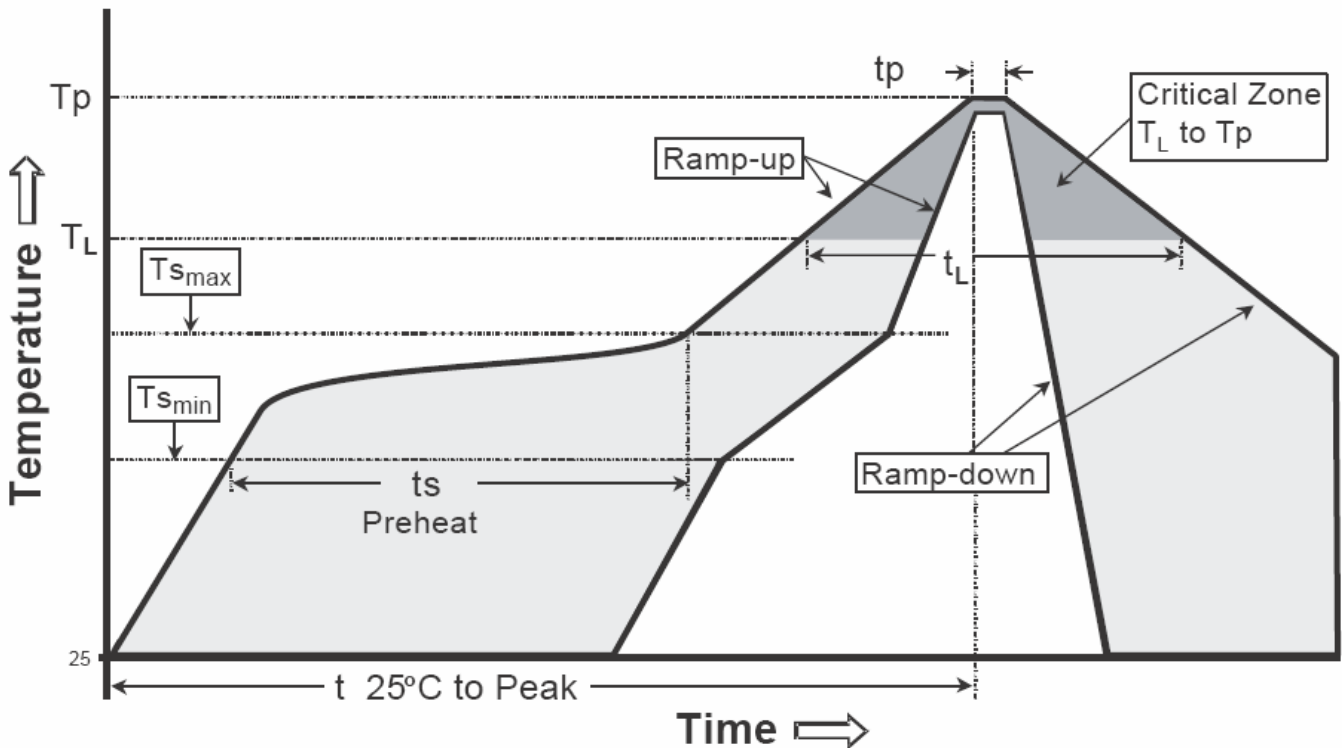
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

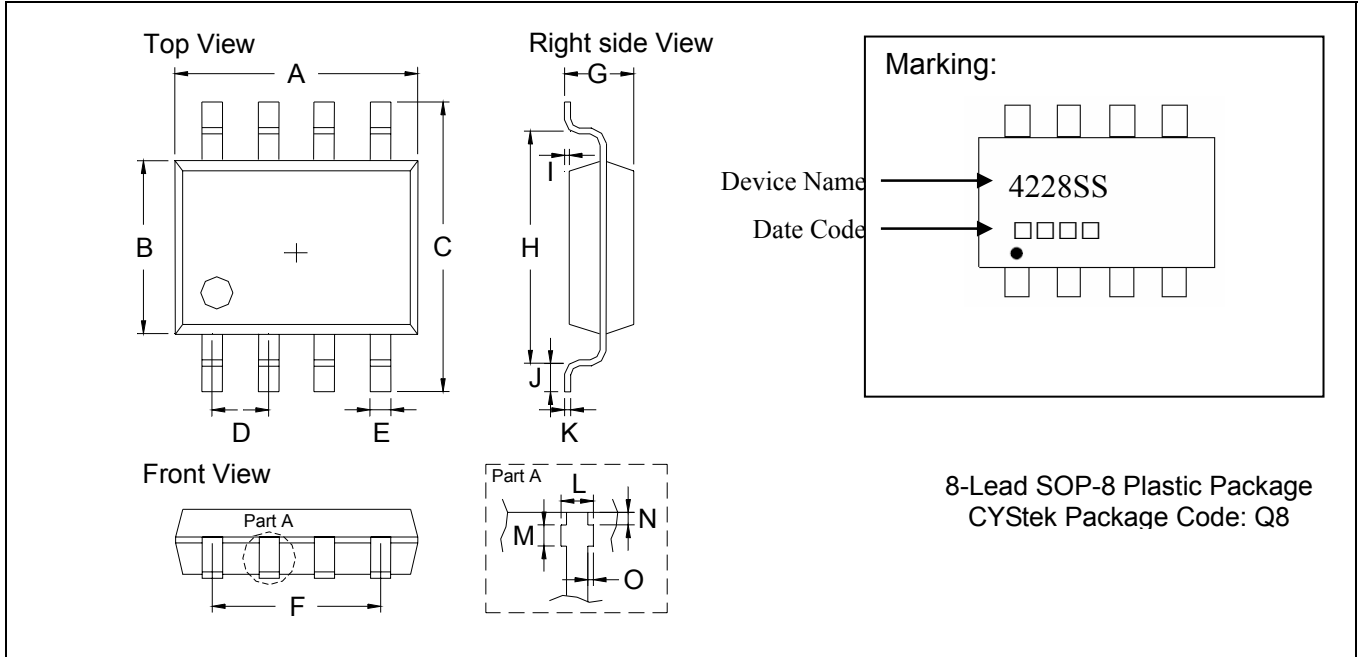
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(Ts min)	100°C	150°C
-Temperature Max(Ts max)	150°C	200°C
-Time(ts min to ts max)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (Tl)	183°C	217°C
- Time (tl)	60-150 seconds	60-150 seconds
Peak Temperature(Tp)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOP-8 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1890	0.2007	4.80	5.10	I	0.0098	REF	0.25	REF
B	0.1496	0.1654	3.80	4.20	J	0.0118	0.0354	0.30	0.90
C	0.2283	0.2441	5.80	6.20	K	0.0074	0.0098	0.19	0.25
D	0.0480	0.0519	1.22	1.32	L	0.0145	0.0204	0.37	0.52
E	0.0138	0.0193	0.35	0.49	M	0.0118	0.0197	0.30	0.50
F	0.1472	0.1527	3.74	3.88	N	0.0031	0.0051	0.08	0.13
G	0.0531	0.0689	1.35	1.75	O	0.0000	0.0059	0.00	0.15
H	0.1889	0.2007	4.80	5.10					

Notes: 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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